

Surface Mount Glass Plassivated Silicon Rectifiers

FEATURES

- Plastic package has carries underwriters
- Ideal for automated placement
- Surge overload rating to 30 Ampers peak
- Reliable low cost construction utilizing molded plastic technique results in in-expensive product
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21 definition



MELF





MECHANICAL DATA

Case: MELF

Molding compound, UL flammability classification rating 94V-0 Packing code with suffix "G" means green compound (halogen-free)

Mounting position: Any

Polarity: Indicated by silver cathode band

Weight: 0.12 g (approximately)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T _A =25°C unless otherwise noted)										
DADAMETED	SYMBOL	LL40	LL40	LL40	LL40	LL40	LL40	LL40	LINIT	
PARAMETER	STIVIBUL	01G	02G	03G	04G	05G	06G	07G	UNIT	
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V	
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V	
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V	
Maximum average forward rectified current	I _{F(AV)}				1				Α	
Peak forward surge current, 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	30			А					
Maximum instantaneous forward voltage (Note 1) @ 1 A	V _F	1.1			V					
Maximum reverse current @ rated VR T_J =25 °C T_J =125 °C	I _R	5 100		μA						
Typical junction capacitance (Note 2)	CJ				15				pF	
Typical thermal resistance	$R_{ heta JC}$				50				°C/W	
Operating junction temperature range	TJ	- 65 to +150			°C					
Storage temperature range	T _{STG}	- 65 to +150				°C				

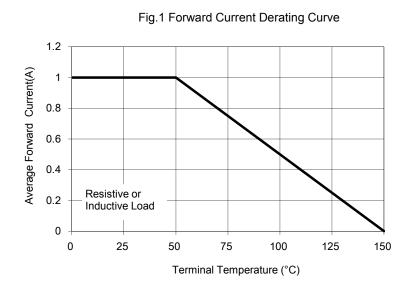
Note 1: Pulse test with PW=300µs, 1% duty cycle

Note 2: Measured at 1 MHz and Applied Reverse Voltage of 4.0V D.C.



RATINGS AND CHARACTERISTICS CURVES

(T_A=25°C unless otherwise noted)



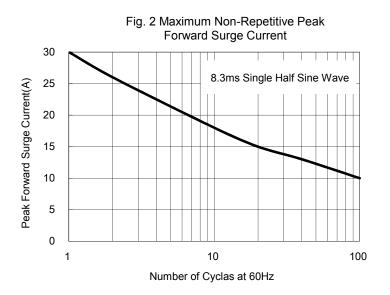
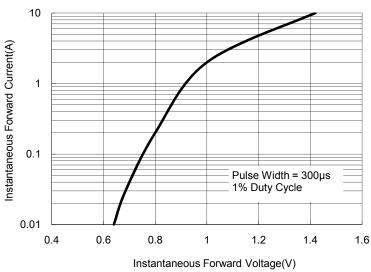
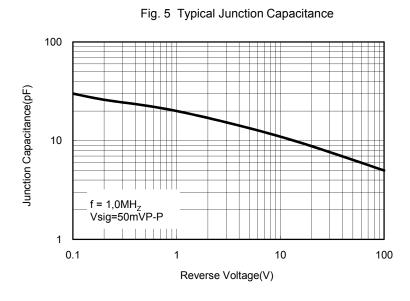


Fig. 3 Instantaneous Forward Characteristics



1000 $T_J = 150^{\circ}C$ Instantaneous Reverse Current(µA) 100 10 $T_{J} = 100^{\circ}C$ 1 $T_J = 25^{\circ}C$ 0.1 0.01 20 40 60 80 100

Fig. 4 Typical Reverse Characteristics



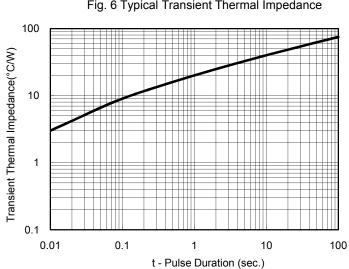
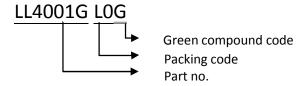


Fig. 6 Typical Transient Thermal Impedance

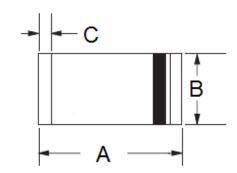
Percentage of Peak Reverse Voltage(%)



ORDER INFORMATION (EXAMPLE)

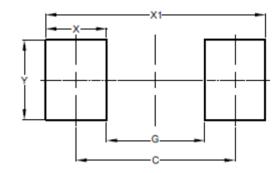


PACKAGE OUTLINE DIMENSIONS MELF



DINA	Unit	Unit (mm)		Unit (inch)			
DIM.	Min	Max	Min	Max			
Α	4.80	5.50	0.189	0.217			
В	2.25	2.67	0.089	0.105			
С	0.30	0.60	0.012	0.024			

SUGGEST PAD LAYOUT



DIM.	Unit (mm)	Unit (inch)		
DIIVI.	Тур.	Тур.		
С	4.80	0.189		
G	3.30	0.130		
Х	1.50	0.059		
X1	6.30	0.248		
Y	2.70	0.106		





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